

ABSTRACT OF THE DISCLOSURE

An optical chassis includes a mount substrate an optoelectronic device on the mount substrate, a spacer substrate, and a sealer substrate. The mount substrate, the spacer substrate and the sealer substrate are vertically stacked and hermetically sealing the optoelectronic device. An external electrical contact for the optoelectronic device is provided outside the sealing. At least part of the optical chassis may be made on a wafer level. A passive optical element may be provided on the sealer substrate or on another substrate stacked and secured thereto.